

Part Number: SBC18-11SURKCGKWA

Hyper Red  
Green

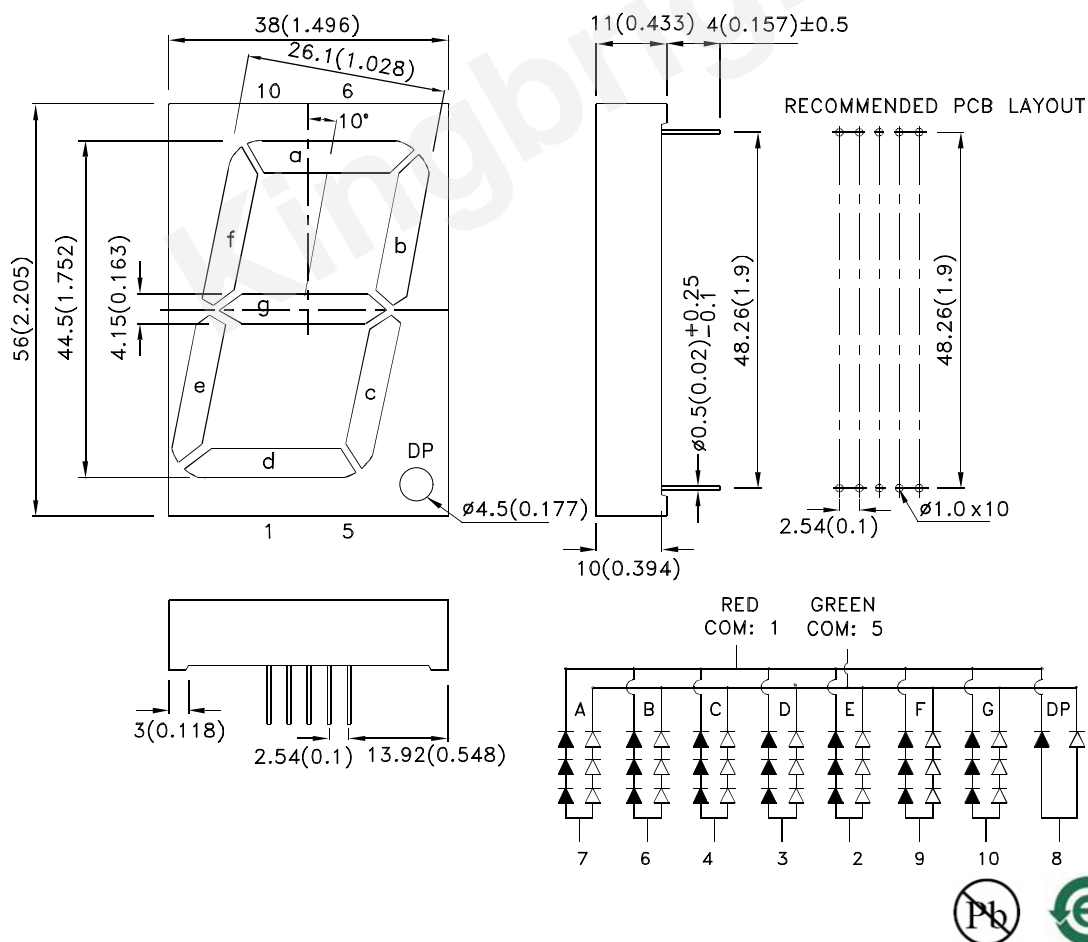
### Features

- 1.75 inch digit height.
- Low current operation.
- Excellent character appearance.
- Easy mounting on P.C. boards or sockets.
- Categorized for luminous intensity.
- Mechanically rugged.
- Standard : gray face, white segment.
- RoHS compliant.

### Descriptions

- The Hyper Red source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.
- The Green source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.

### Package Dimensions & Internal Circuit Diagram



#### Notes:

1. All dimensions are in millimeters (inches), Tolerance is  $\pm 0.25(0.01)$  unless otherwise noted.
2. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

## Selection Guide

Part No.	Emitting Color (Material)	Lens Type	Iv (ucd) [1] @ 10mA		Description
			Min.	Typ.	
SBC18-11SURKCGKWA	Hyper Red (AlGaInP)	White Diffused	150000	310000	Common Cathode ,Rt. Hand Decimal.
			*31000	*90000	
	Green (AlGaInP)		52000	140000	
			*21000	*50000	

### Notes:

1. Luminous intensity / luminous Flux: +/-15%.

\* Luminous intensity value is traceable to CIE127-2007 standards.

## Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Emitting Color	Typ.	Max.	Units	Test Conditions
$\lambda_{peak}$	Peak Wavelength	Hyper Red Green	645 574		nm	IF=10mA
$\lambda_D$ [1]	Dominant Wavelength	Hyper Red Green	630 570		nm	IF=10mA
$\Delta\lambda_{1/2}$	Spectral Line Half-width	Hyper Red Green	28 20		nm	IF=10mA
C	Capacitance	Hyper Red Green	35 15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage (DP)	Hyper Red Green	5.55 (1.85) 6 (2)	7.5 (2.5) 7.5 (2.5)	V	IF=10mA
IR	Reverse Current (Per Chip)	Hyper Red Green		10	uA	VR=5V

### Notes:

1. Wavelength: +/-1nm.

2. Forward Voltage: +/-0.1V.

3. Wavelength value is traceable to CIE127-2007 standards.

4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

## Absolute Maximum Ratings at TA=25°C

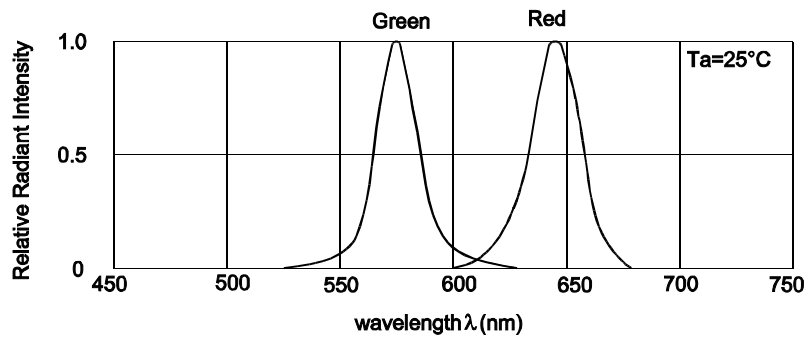
Parameter	Hyper Red	Green	Units
Power dissipation (Per Chip)	75	75	mW
DC Forward Current (DP)	30 (30)	30 (30)	mA
Peak Forward Current [1] (DP)	185 (185)	150 (150)	mA
Reverse Voltage (Per Chip)	5		V
Operating/Storage Temperature	-40°C To +85°C		
Lead Solder Temperature [2]	260°C For 3-5 Seconds		

### Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

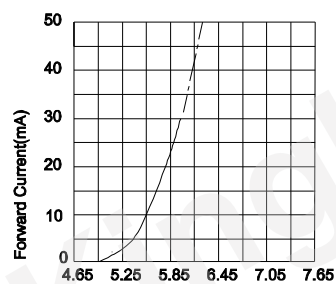
2. 2mm below package base.

3. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

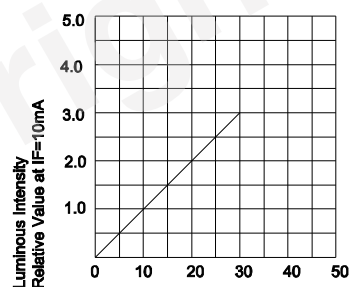


Relative Intensity Vs. Wavelength

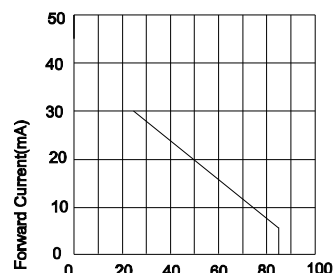
## SBC18-11SURKCGKWA Hyper Red



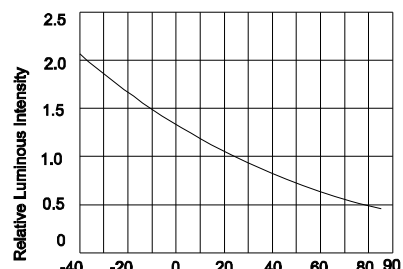
Forward Voltage(V)  
FORWARD CURRENT Vs  
FORWARD VOLTAGE



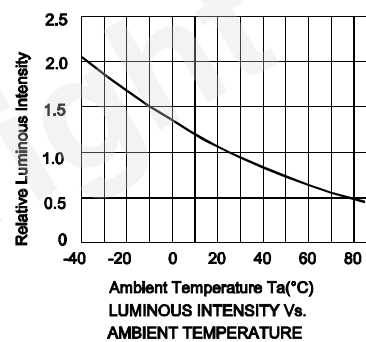
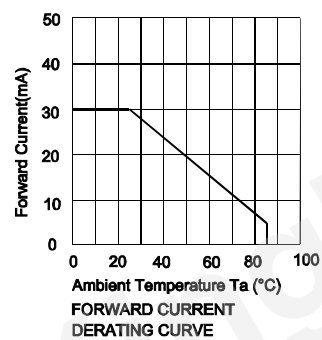
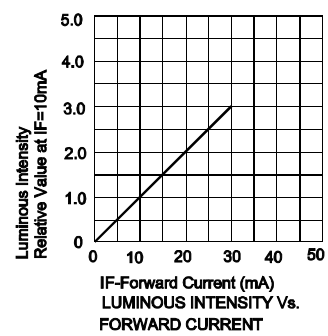
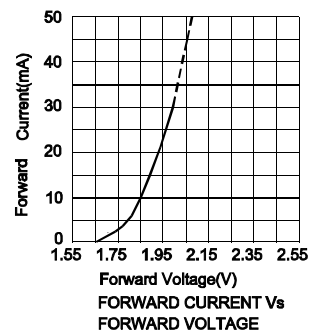
IF-Forward Current (mA)  
LUMINOUS INTENSITY Vs.  
FORWARD CURRENT



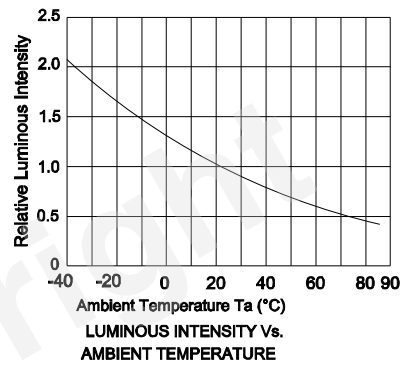
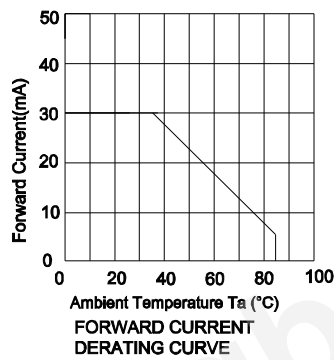
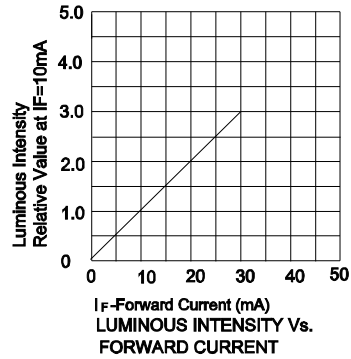
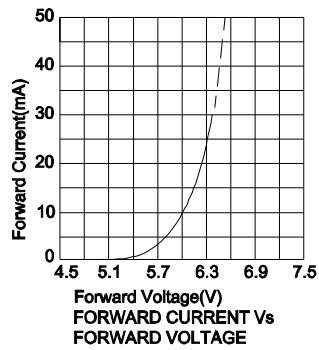
Ambient Temperature  $T_A$  ( $^\circ\text{C}$ )  
FORWARD CURRENT  
DERATING CURVE

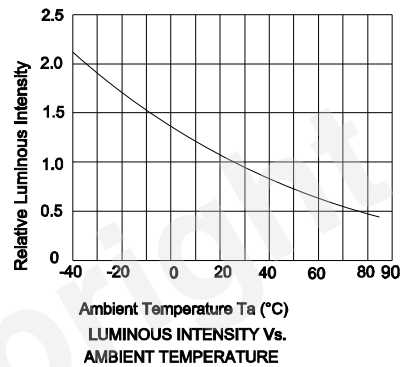
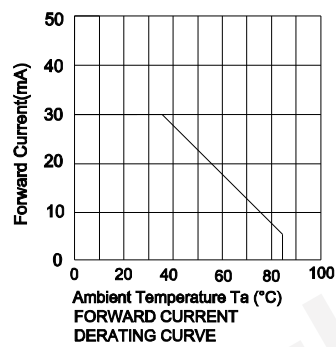
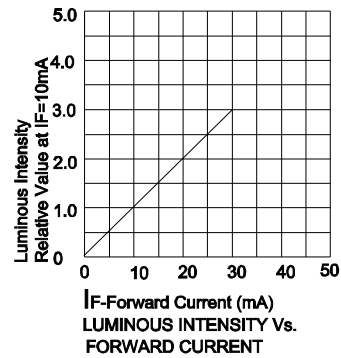
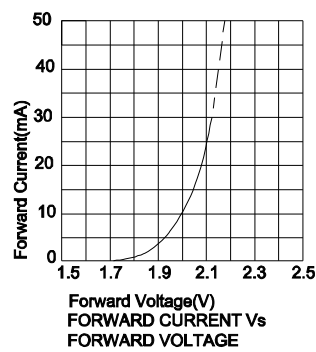


Ambient Temperature  $T_A$  ( $^\circ\text{C}$ )  
LUMINOUS INTENSITY Vs.  
AMBIENT TEMPERATURE



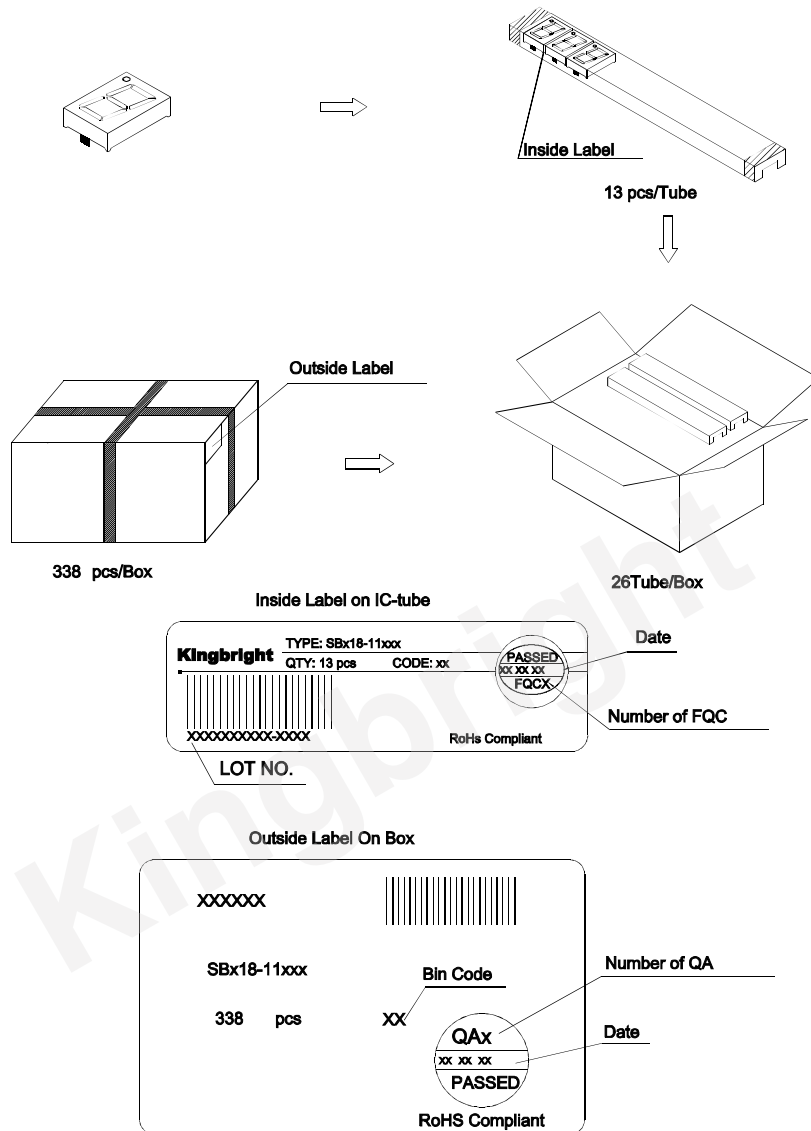
Green





## PACKING & LABEL SPECIFICATIONS

## SBC18-11SURKCGKWA



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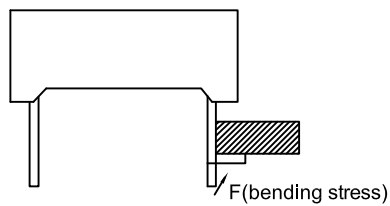
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## Through Hole Display Mounting Method

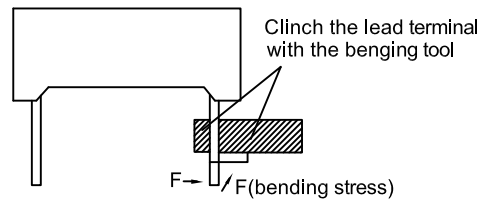
### Lead Forming

Do not bend the component leads by hand without proper tools.

The leads should be bent by clinching the upper part of the lead firmly such that the bending force is not exerted on the plastic body.



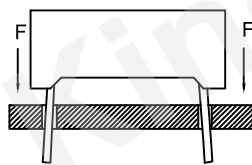
Not Recommended



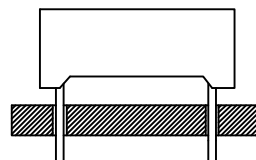
Recommended

### Installation

1. The installation process should not apply stress to the lead terminals.
2. When inserting for assembly, ensure the terminal pitch matches the substrate board's hole pitch to prevent spreading or pinching the lead terminals.

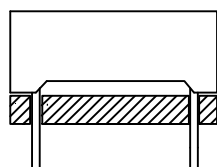


Not Recommended

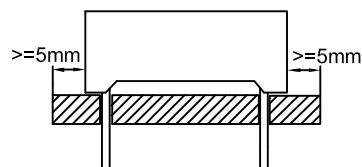


Recommended

3. The component shall be placed at least 5mm from edge of PCB to avoid damage caused excessive heat during wave soldering.

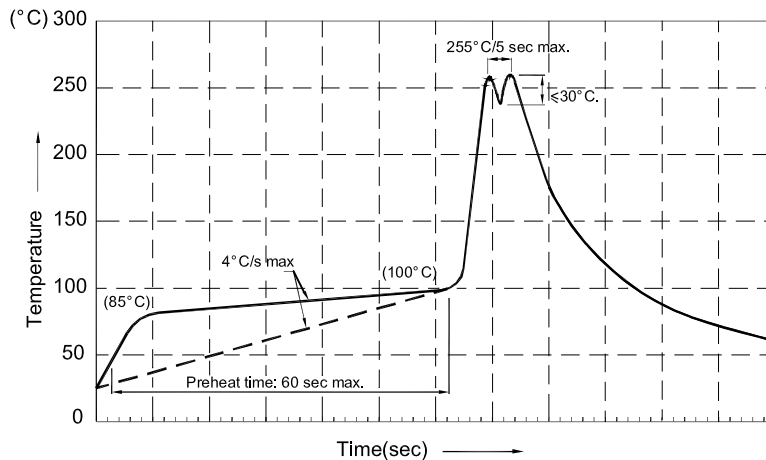


Not Recommended



Recommended

## Recommended Wave Soldering Profiles:



### Notes:

1. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
3. Do not apply stress to the epoxy resin while the temperature is above 85°C.
4. Fixtures should not incur stress on the component when mounting and during soldering process.
5. SAC 305 solder alloy is recommended.
6. No more than one wave soldering pass.
7. During wave soldering, the PCB top-surface temperature should be kept below 105°C.

## Soldering General Notes:

1. Through-hole displays are incompatible with reflow soldering.
2. If components will undergo multiple soldering processes, or other processes where the components may be subjected to intense heat, please check with Kingbright for compatibility.

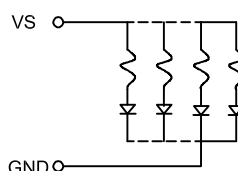
## Cleaning

1. Mild "no-clean" fluxes are recommended for use in soldering.
2. If cleaning is required, Kingbright recommends to wash components with water only. Do not use harsh organic solvents for cleaning because they may damage the plastic parts.
3. The cleaning process should take place at room temperature and the devices should not be washed for more than one minute.
4. When water is used in the cleaning process, immediately remove excess moisture from the component with forced-air drying afterwards.

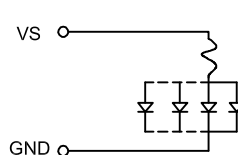
## Circuit Design Notes

1. Protective current-limiting resistors may be necessary to operate the LEDs within the specified range.
2. LEDs mounted in parallel should each be placed in series with its own current-limiting resistor.

Recommended Set-up



Invalid Set-up



3. The driving circuit should be designed to protect the LED against reverse voltages and transient voltage spikes when the circuit is powered up or shut down.
4. The safe operating current should be chosen after considering the maximum ambient temperature of the operating environment.
5. Prolonged reverse bias should be avoided, as it could cause metal migration, leading to an increase in leakage current or causing a short circuit.